

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

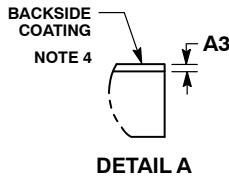
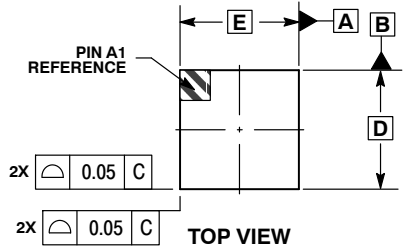
ON Semiconductor®



SCALE 4:1

WLCSP9, 1.31x1.31
CASE 567HX
ISSUE C

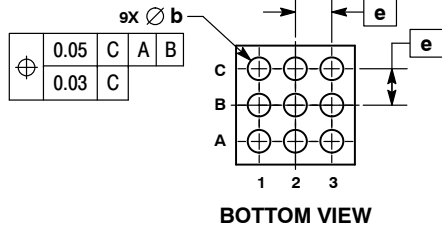
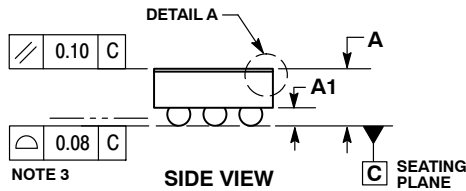
DATE 22 APR 2015



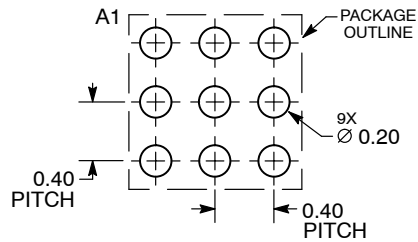
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. BACKSIDE COATING IS OPTIONAL.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.65
A1	0.16	0.26
A3	0.025 REF	
b	0.21	0.31
D	1.31 BSC	
E	1.31 BSC	
e	0.40 BSC	



RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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